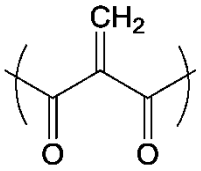
CLAIMS

1. An adhesive, sealing material, film or prepreg for an electronic component comprising a resin composition comprising one or more 2-methylene-1,3-dicarbonyl compounds, wherein

at least one of the one or more 2-methylene-1,3-dicarbonyl compounds has a molecular weight of 220 to 10,000;

the amount by weight of those of the 2-methylene-1,3-dicarbonyl compounds having a molecular weight of less than 220 relative to the totality of the 2-methylene-1,3-dicarbonyl compounds of 1 is 0.00 to 0.05; and

the 2-methylene-1,3-dicarbonyl compounds comprise a structural unit represented by formula (I) below.



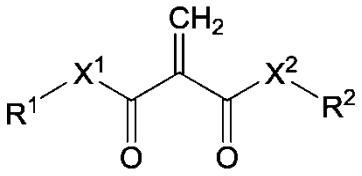
(I)

2. The adhesive, sealing material, film or prepreg according to claim 1, wherein the amount by weight of those of the 2-methylene-1,3-dicarbonyl compounds having a molecular weight of less than 220 relative to the totality of the 2-methylene-1,3-dicarbonyl compounds of 1 is 0.00 to 0.01.

3. The adhesive, sealing material, film or prepreg according to claim 1 or 2, comprising at least one 2-methylene-1,3-dicarbonyl compound comprising two or more structural units represented by formula (I) above.

4. The adhesive, sealing material, film or prepreg according to claim 3, wherein the amount by weight of the at least one 2-methylene-1,3-dicarbonyl compound comprising two or more structural units represented by formula (I) above relative to the totality of the 2-methylene-1,3-dicarbonyl compounds of 1 is 0.05 to 0.95.

5. The adhesive, sealing material, film or prepreg according to any one of claims 1 to 4, wherein the 2-methylene-1,3-dicarbonyl compounds are represented by formula (II) below:

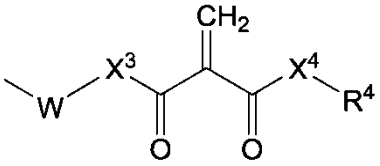


(II)

wherein

X^1 and X^2 each, independently, represent a single bond, O or NR^3, wherein R^3 represents hydrogen or a monovalent hydrocarbon group; and

R^1 and R^2 are each, independently, hydrogen, a monovalent hydrocarbon group, or represented by formula (III) below:



(III)

wherein

X^3 and X^4 each, independently, represent a single bond, O or NR^5, wherein R^5 represents hydrogen or a monovalent hydrocarbon group;

W represents a spacer; and

R^4 represents hydrogen or a monovalent hydrocarbon group.

6. The adhesive, sealing material, film or prepreg according to any one of claims 1 to 5, further comprising (A) an inorganic filler.

7. The adhesive, sealing material, film or prepreg according to any one of claims 1 to 6, further comprising (B) a curing catalyst.

8. The adhesive, sealing material, film or prepreg according to any one of claims 1 to 7, further comprising (C) a stabilizer.

9. The adhesive, sealing material, film or prepreg according to any one of claims 1 to 8, wherein the amount by weight of the 2-methylene-1,3-dicarbonyl compounds relative to the entire resin composition is 0.01 to 1.00.

10. The adhesive, sealing material, film or prepreg according to any one of claims 1 to 9, wherein the amount by weight of those of the 2-methylene-1,3-dicarbonyl compounds having a vapor pressure of 0.01 mmHg or more at 25°C relative to the totality of the 2-methylene-1,3-dicarbonyl compounds of 1 is 0.00 to 0.05.

11. The adhesive, sealing material, film or prepreg according to any one of claims 1 to 10, curable by heat.

12. A semiconductor device comprising the adhesive, sealing material, film or prepreg according to any one of claims 1 to 11.